





Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- \bullet Reliable & robust
- Custom color combinations available
- RoHS Compliant

Dec 23,2013





Package Schematics 10.29[0.405] 1.14[0.045] 5.08[0.2] 0.2[0.008]MAX.GAP 0.686[0.027]MAX 0.686[0.027]MAX 0.15[0.006] 1.02[0.04] 2.54[0.1] CATHODE

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		UY (GaAsP/GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds			
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds			

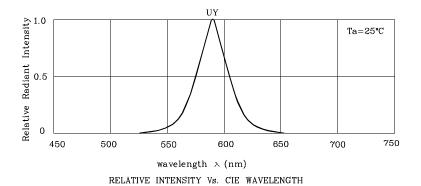
Operating Characteristics $(T_A=25^{\circ}C)$		UY (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2.1	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	20	pF

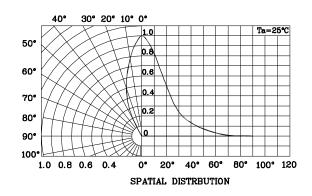
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous \ Intensity \\ CIE127\text{-}2007* \\ (I_F\text{=}20\text{mA}) \\ mcd \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XNF4ZUY46D	Yellow	GaAsP/GaP	Yellow Diffused	5*	9*	590*	40°

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

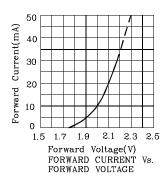


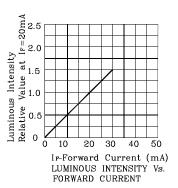


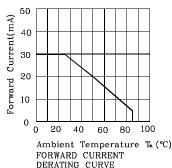


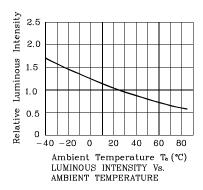


UY

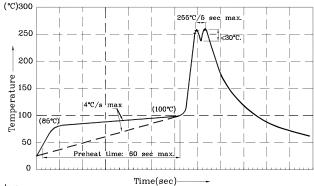








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C \sim 255^{\circ}C$ for 3 sec
- (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above $85\,^\circ\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

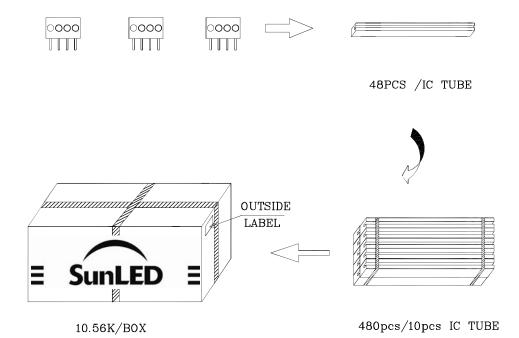
the typical accuracy of the sorting process is as follows:

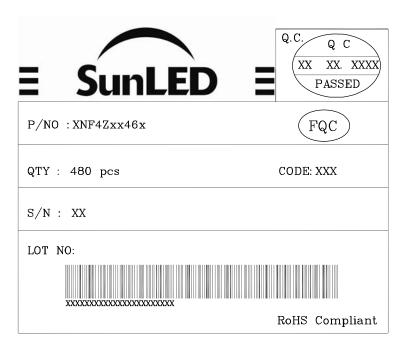
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

SUBMINIATURE SOLID STATE LAMP

PACKING & LABEL SPECIFICATIONS





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